

FIG. 1

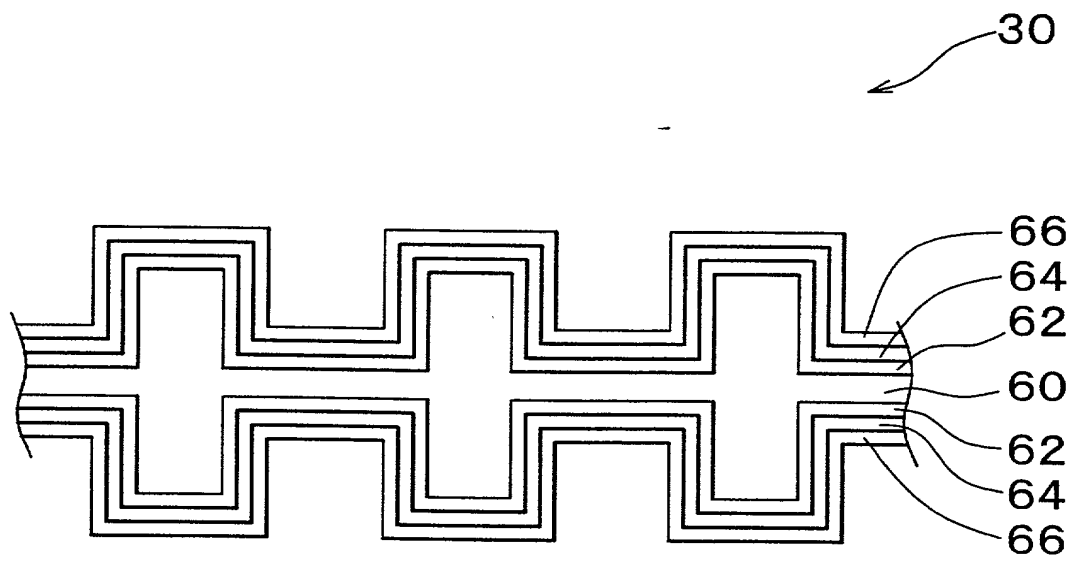


FIG. 2

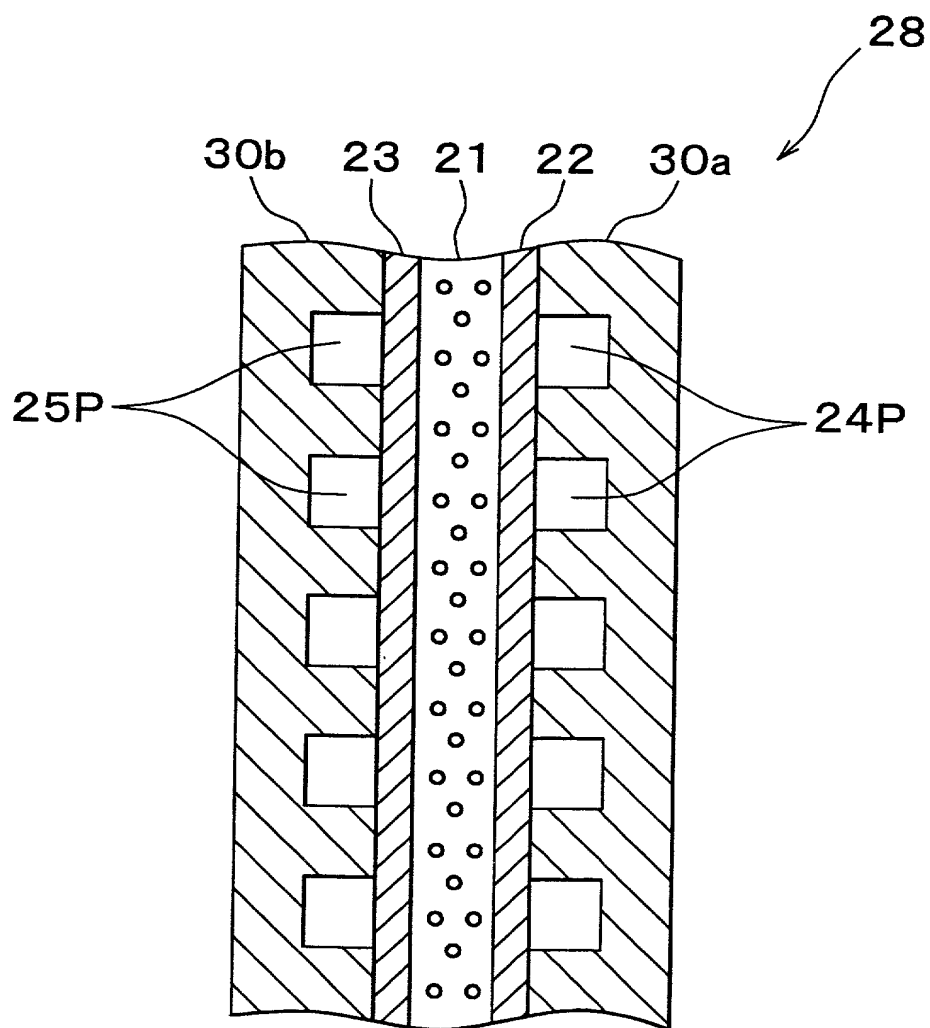


FIG. 3

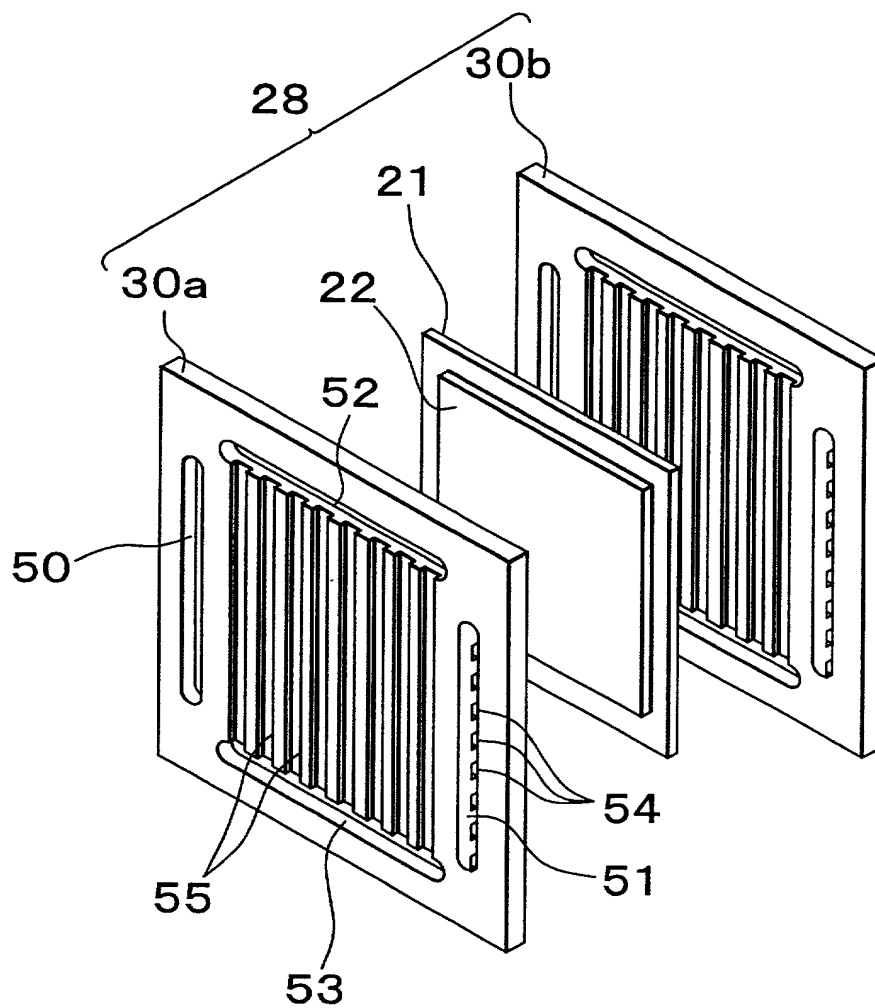
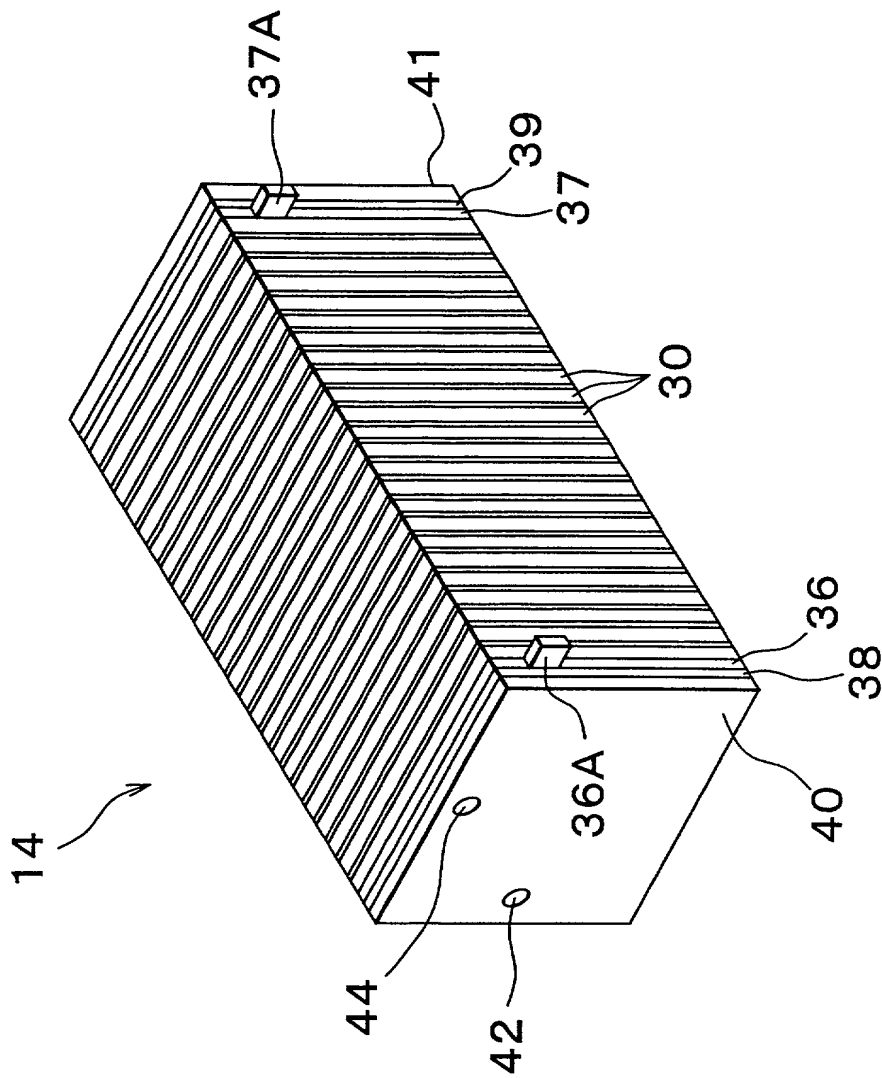
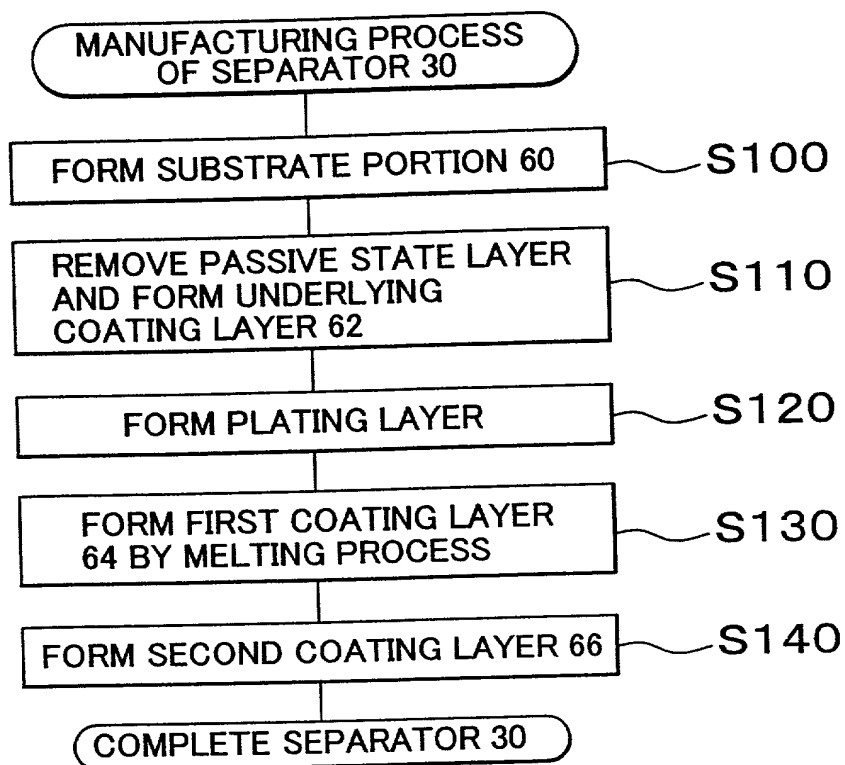


FIG. 4



# FIG. 5



# FIG. 6

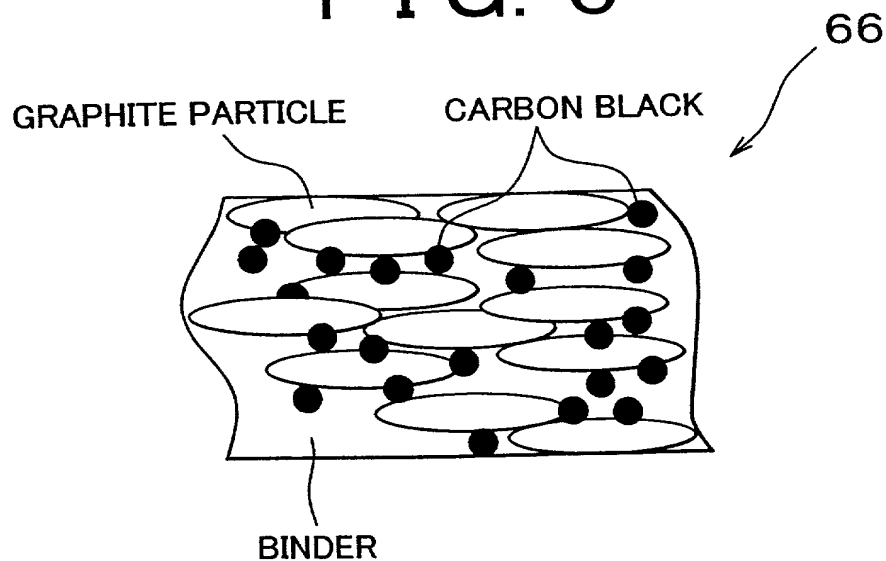


FIG. 7A

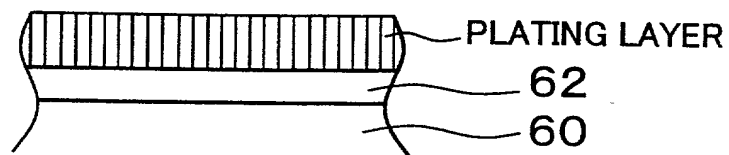


FIG. 7B

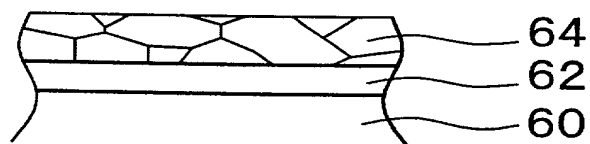


FIG. 7C

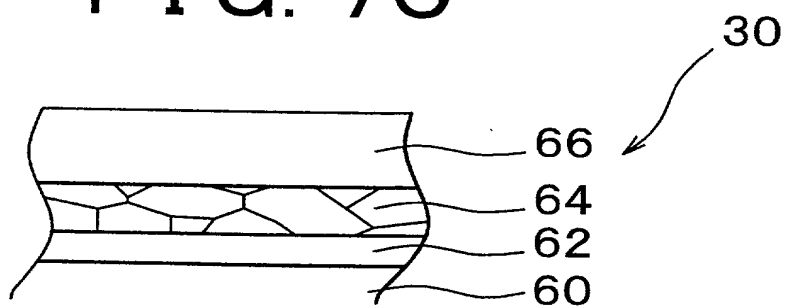
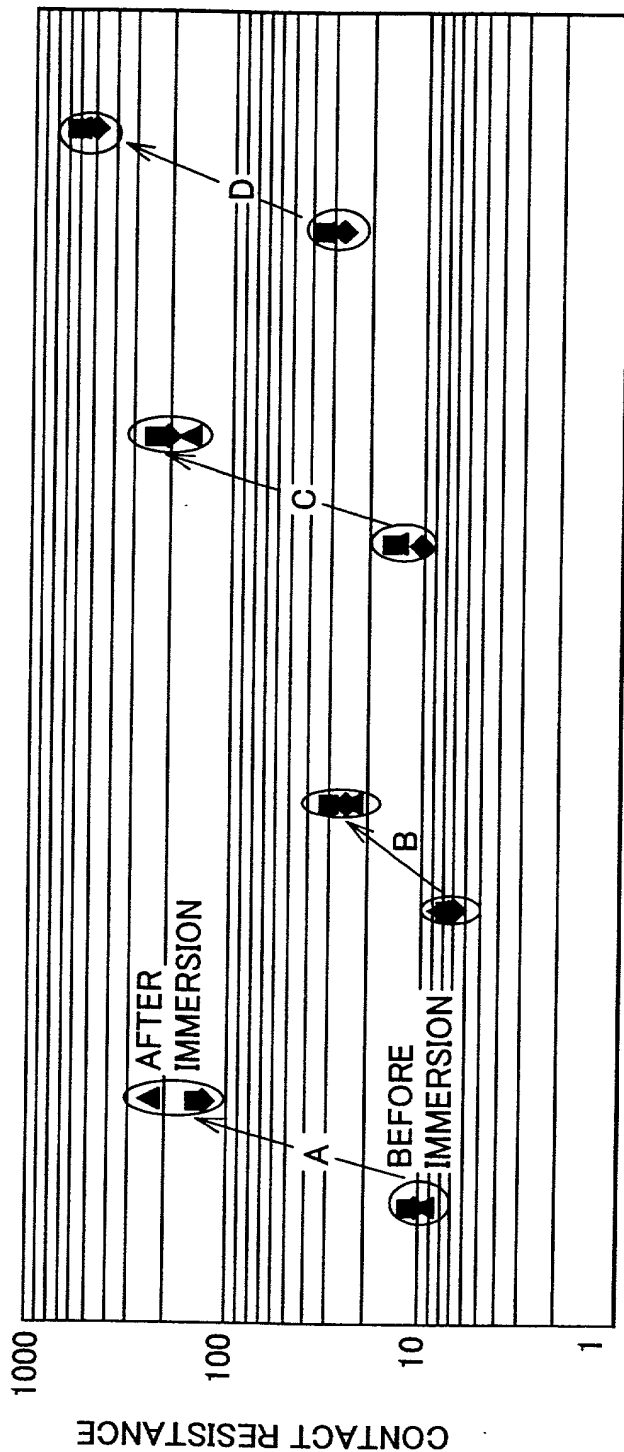


FIG. 8



- A : Sn-Bi, WITHOUT MELTING PROCESS
- B : Sn-Bi, WITH MELTING PROCESS ( AIR-COOLING )
- C : Sn-Bi, WITH MELTING PROCESS ( WATER-COOLING )
- D : Sn, WITH MELTING PROCESS ( AIR-COOLING )

FIG. 9

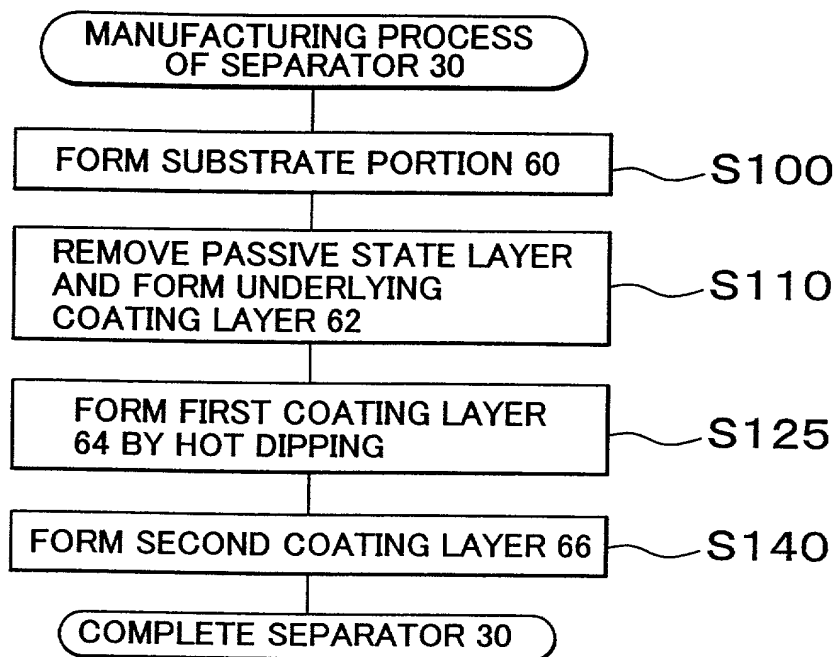
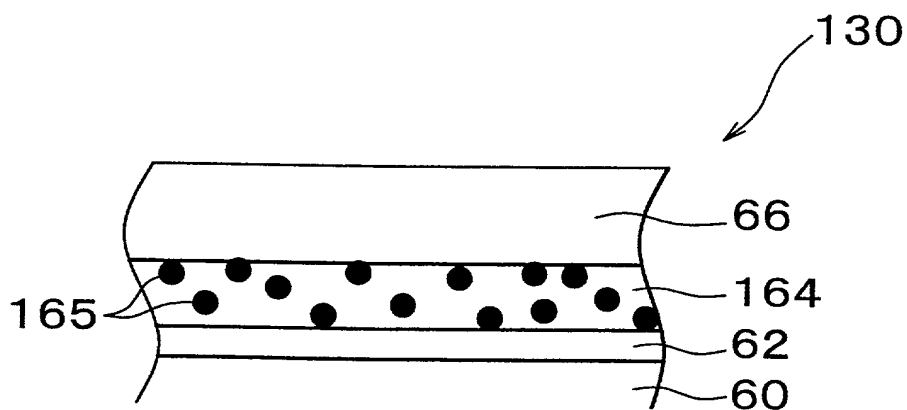
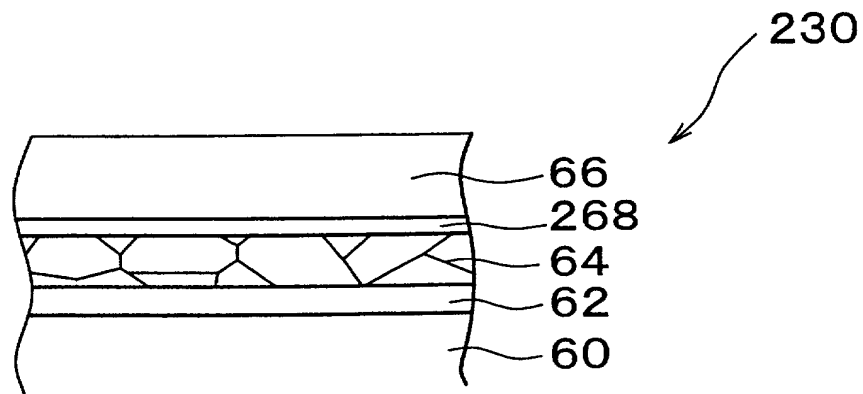


FIG. 10





# FIG. 11



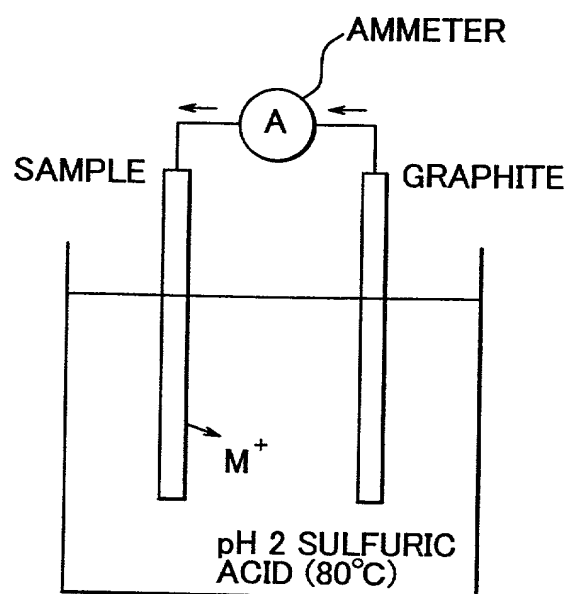
# FIG. 12

SURFACE TREATMENT	CORROSION CURRENT * <sup>1</sup> ( $\mu\text{A}/\text{cm}^2$ )	CONTACT RESISTANCE * <sup>2</sup> ( $\text{m}\Omega\text{cm}^2$ )
E:0.1 $\mu\text{mAg}/10\mu\text{mCu}$	6.9	10 OR LESS
F:0.1 $\mu\text{mAg}/10\mu\text{mSn}$ (UNPROCESSED) /10 $\mu\text{mCu}$	21.9	10 OR LESS
G:0.1 $\mu\text{mAg}/10\mu\text{mSn}$ (MELTING PROCESS) /10 $\mu\text{mCu}$	0.3	10 OR LESS

\* 1: RESULT OBTAINED WITHOUT CARBON COATING LAYER OF CARBON MATERIALS

\* 2: RESULT OBTAINED WITH CARBON COATING LAYER OF CARBON MATERIALS

FIG. 13



09837480 041901  
T06TH0 08448860

FIG. 14

SEPARATOR BASE MATERIAL *	PREDETER MINED PROCESS *	METAL COATING LAYER *	CONDUCTIVE PARTICLES *	CORROSION -RESISTANT COATING LAYER *	CARBON CORROTING LAYER *
PRESENT	PRESENT  NONE	METAL HAVING LOWER MELTING POINT THAN MATERIAL OF SEPARATOR BASE MATERIAL AND HAVING BEEN SUBJECTED TO MELTING PROCESS OR METAL HAVING CRYSTAL GRAIN SIZE OF 0.1 mm OR MORE	PRESENT  NONE	PRESENT  NONE	PRESENT  NONE

\* : ANY MATERIAL AS DESCRIBED IN THE SPECIFICATION  
CAN BE SELECTED AS APPROPRIATE